

8 wafer Fully automatic final cleaning machine

Model: SA-FCM-48LS

SA-FCM-48LS adopts advanced cassette-less transmission and professional drying technologies to finally remove surface contaminants. It applies megasonic circulation cleaning for superior cleaning quality. The equipment supports connection with management systems and maintains excellent particle and metal ion control. It runs stably and efficiently, fully meeting the strict final cleaning standards for semiconductor wafers.



Feature

- Cassetteless
- Megasonic Circulation Cleaning
- Support MES system
- Pull IR or Marangoi Drying

Application

- Polished Silicon Wafer
- Epitaxial Wafer
- Particle and Metal Ion

Specifications:

Parameter	Descriptions
Wafer Size	8"(Compatible with 6")
Processing Capacity	50 wafers /tank time
Solution Temperature	50°C~80°C±1°C
Megasonic Cleaning	950KHz,400W
Solution Accuracy Error	≤ 1%
Metal Ions	≤ 5E10 atoms/cm ²
Particle Control	≤ 10 pieces/wafer@0.3μm ≤ 20 pieces/wafer@0.2μm
Production Efficiency	≥ 275 wafers/hour